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FDMC8026S

# N-Channel PowerTrench<sup>®</sup> SyncFET<sup>TM</sup> 30 V, 21 A, 4.4 m $\Omega$

#### **Features**

- Max  $r_{DS(on)} = 4.4 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 19 \text{ A}$
- Max  $r_{DS(on)} = 5.2 \text{ m}\Omega$  at  $V_{GS} = 4.5 \text{ V}$ ,  $I_D = 17.5 \text{ A}$
- Advanced package and silicon combination for low r<sub>DS(on)</sub> and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

# **General Description**

The FDMC8026S has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest  $r_{\text{DS}(\text{on})}$  while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic schottky body diode.

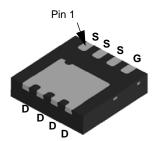
## **Applications**

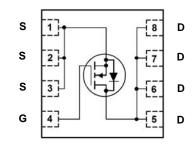
- Synchronous Rectifier for DC/DC Converters
- Notebook Vcore/GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification











MLP 3.3x3.3

# MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Paramete	Ratings	Units			
V <sub>DS</sub>	Drain to Source Voltage			30	V	
$V_{GS}$	Gate to Source Voltage		(Note 4)	±20	V	
	Drain Current -Continuous	T <sub>C</sub> = 25°C		21		
$I_D$	-Continuous	T <sub>A</sub> = 25°C	(Note 1a)	19	Α	
	-Pulsed			100		
E <sub>AS</sub>	Single Pulse Avalance Energy		(Note 3)	66	mJ	
В	Power Dissipation	T <sub>C</sub> = 25°C		36	W	
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	2.4	VV	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperatu	ıre Range		-55 to +150	°C	

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a	53	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC8026S	FDMC8026S	MLP 3.3X3.3	13 "	12 mm	3000 units

# **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units			
Off Characteristics									
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0 V	30			V			
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, referenced to 25 °C		26		mV/°C			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V			500	μΑ			
$I_{GSS}$	Gate to Source Leakage Current, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA			

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 1$ mA	1.2	1.6	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, referenced to 25 °C		-5		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19 A		3.8	4.4	- mΩ
		$V_{GS} = 4.5 \text{ V}, I_D = 17.5 \text{ A}$		4.5	5.2	
		$V_{GS} = 10 \text{ V}, I_D = 19 \text{ A},$ $T_J = 125 ^{\circ}\text{C}$		4.5	5.8	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 19 A		106		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		2380	3165	pF
C <sub>oss</sub>	Output Capacitance			885	1175	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			100	150	pF
R <sub>g</sub>	Gate Resistance		0.1	0.7	2.5	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		11	20	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 19 A,	5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	30	48	ns
t <sub>f</sub>	Fall Time		4	10	ns
$Q_{g}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	37	52	nC
$Q_{g}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V} V_{DD} = 15 \text{ V},$	18	25	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 19 A	6		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		6		nC

#### **Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)	0.6	0.8	V
	Source to Drain blode Forward Voltage	$V_{GS} = 0 \text{ V, } I_{S} = 19 \text{ A}$ (Note 2)	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>E</sub> = 19 A, di/dt = 300 A/μs	29	47	ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 19 A, α/αι = 300 A/μs	33	53	nC

Notes:

1. R<sub>BJA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>BJC</sub> is guaranteed by design while R<sub>BCA</sub> is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0%.

<sup>3.</sup> E<sub>AS</sub> of 66 mJ is based on starting T<sub>J</sub> = 25 °C, L = 0.3 mH, I<sub>AS</sub> = 21 A, V<sub>DD</sub> = 27 V, V<sub>GS</sub> = 10 V. 100% tested at L = 3 mH, I<sub>AS</sub> = 10.2 A.

<sup>4.</sup> As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

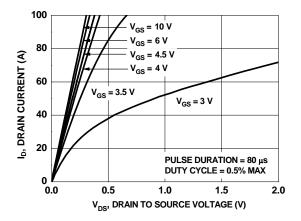


Figure 1. On Region Characteristics

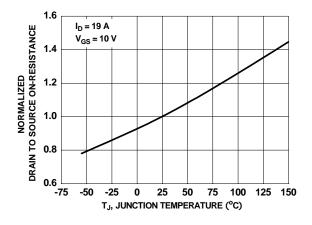


Figure 3. Normalized On Resistance vs. Junction Temperature

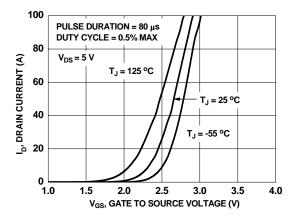


Figure 5. Transfer Characteristics

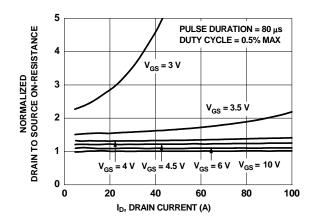


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

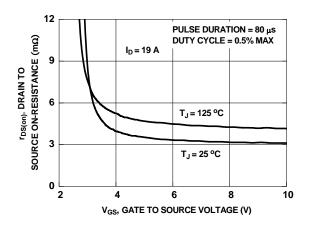


Figure 4. On-Resistance vs. Gate to Source Voltage

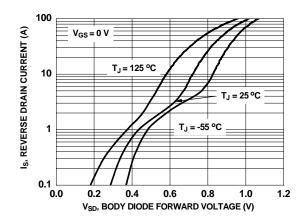


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

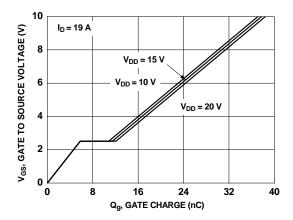


Figure 7. Gate Charge Characteristics

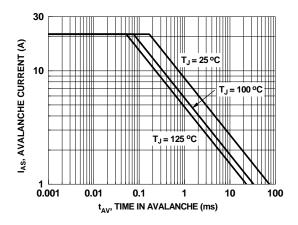


Figure 9. Unclamped Inductive Switching Capability

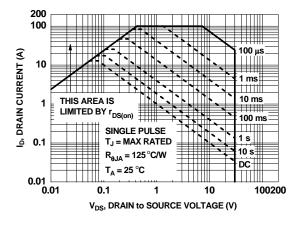


Figure 11. Forward Bias Safe Operating Area

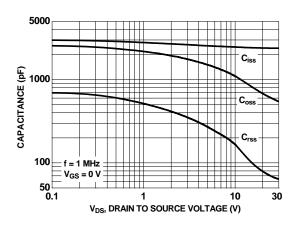


Figure 8. Capacitance vs. Drain to Source Voltage

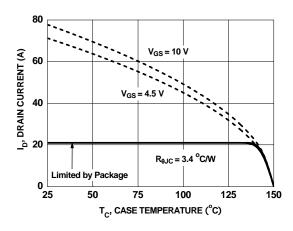


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

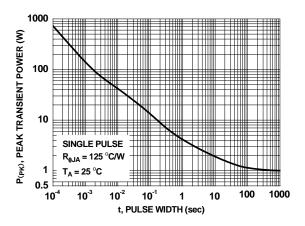


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

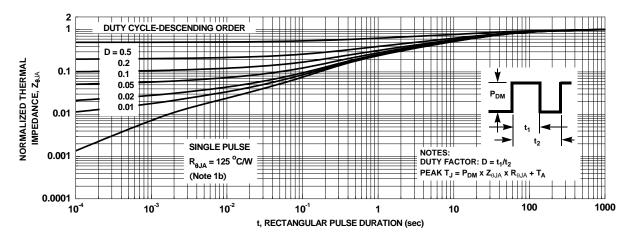


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

# Typical Characteristics (continued)

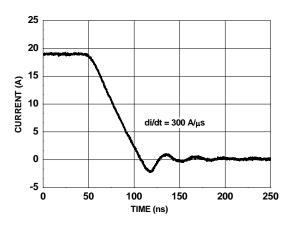
## SyncFET<sup>TM</sup> Schottky body diode Characteristics

Fairchild's SyncFET<sup>TM</sup> process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMC8026S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

T<sub>J</sub> = 125 °C

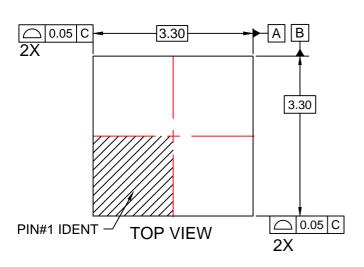
0.01

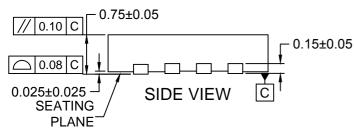


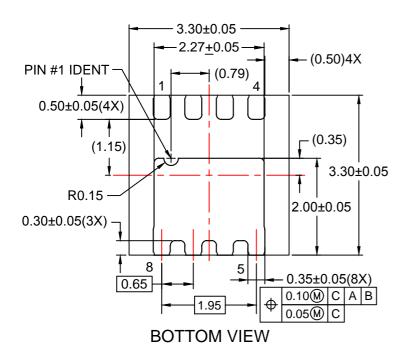
T<sub>J</sub> = 100 °C T,1 = 25 °C 10 15 20 V<sub>DS</sub>, REVERSE VOLTAGE (V)

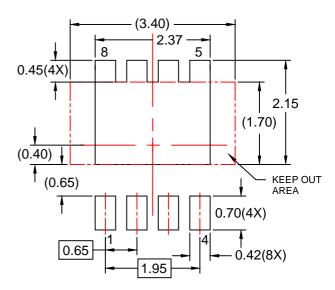
Figure 14. FDMC8026S SyncFET<sup>TM</sup> Body Diode Reverse Recovery Characteristic

Figure 15. SyncFET<sup>TM</sup> Body Diode Reverse Leakage vs. Drain-Source Voltage









RECOMMENDED LAND PATTERN

#### NOTES:

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- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP08Srev3.



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